# NSR20F40NXT5G

# **Schottky Barrier Diode**

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

#### **Features**

- Very Low Forward Voltage Drop 550 mV @ 2.0 A
- Low Reverse Current 15 μA @ 10 V VR
- 2.0 A of Continuous Forward Current
- Power Dissipation of 665 mW with Minimum Trace
- ESD Rating Human Body Model: Class 3B
  - Machine Model: Class C
- Very High Switching Speed
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

# **Typical Applications**

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

#### **Markets**

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

#### **MAXIMUM RATINGS**

	Rating	Symbol	Value	Unit
Reverse Voltage		$V_{R}$	40	V
Forward Current	(DC)	I <sub>F</sub>	2.0	Α
Forward Surge C	Current (60 Hz @ 1 cycle)	I <sub>FSM</sub>	28	Α
	etitive Peak Forward Current se Wave = 1 sec, Duty Cycle = 66%)		4.0	Α
ESD Rating:	Human Body Model Machine Model	ESD	> 8 > 400	kV V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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# **40 V SCHOTTKY BARRIER DIODE**





# (0603)CASE 152AB

### **MARKING DIAGRAM**



20F40 = Specific Device Code = Year Code

# **ORDERING INFORMATION**

Device	Package	Shipping†
NSR20F40NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### NSR20F40NXT5G

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T <sub>A</sub> = 25°C	$egin{array}{c} R_{ hetaJA} \ P_D \end{array}$			213 586	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T <sub>A</sub> = 25°C	R <sub>θJA</sub> P <sub>D</sub>			80 1.56	°C/W W
Storage Temperature Range	T <sub>stg</sub>			-40 to +125	°C
Junction Temperature	TJ			+150	°C

- 1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
- 2. Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V <sub>R</sub> = 10 V) (V <sub>R</sub> = 40 V)	I <sub>R</sub>			15 150	μА
Forward Voltage (I <sub>F</sub> = 1.0 A) (I <sub>F</sub> = 2.0 A)	V <sub>F</sub>			0.47 0.55	V

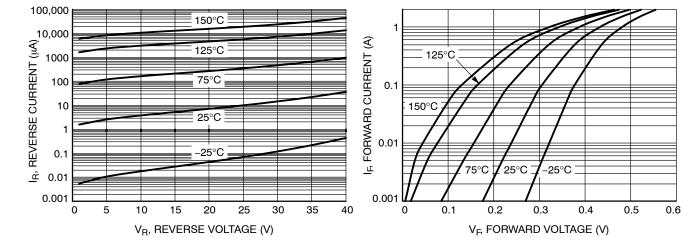


Figure 1. Reverse Current vs. Reverse Voltage

Figure 2. Forward Current vs. Forward Voltage

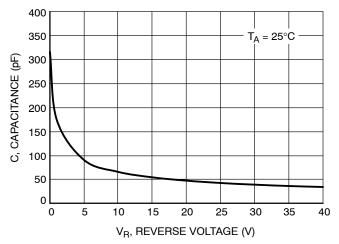
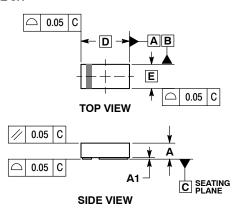


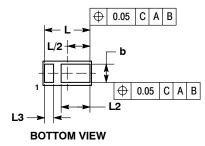
Figure 3. Capacitance



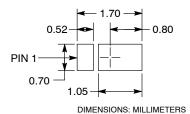
DSN2, 1.6x0.8, 0.9P, (0603) CASE 152AB **ISSUE C** 

**DATE 30 APR 2017** 





#### **MOUNTING FOOTPRINT\***



See Application Note AND8464/D for more mounting details

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.25	0.31	
A1		0.05	
b	0.55	0.65	
D	1.60 BSC		
Е	0.80 BSC		
L	1.45	1.55	
L2	0.90	1.00	
13	0.25	0.35	

# **GENERIC MARKING DIAGRAM1\***



XXXX = Specific Device Code YYY = Year Code

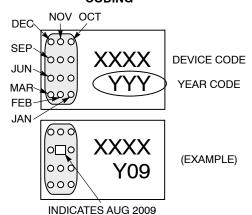
### **GENERIC MARKING DIAGRAM2\***



XX = Specific Device Code M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking

### **CATHODE BAND MONTH** CODING



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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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